RELIABILITY REPORT

FOR

MAX9618AXA+

PLASTIC ENCAPSULATED DEVICES

January 18, 2013

MAXIM INTEGRATED

160 RIO ROBLES

SAN JOSE, CA 95134

Approved by
Sokhom Chum
Quality Assurance
Reliability Engineer

Conclusion

The MAX9618AXA+ successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX9617-MAX9620 are low-power, zero-drift operational amplifiers available in space-saving SC70 packages. They are designed for use in portable consumer, medical, and industrial applications. The MAX9617-MAX9620 feature rail-to-rail CMOS inputs and outputs, a 1.5MHz GBW at just 59µA supply current and 10µV (max) zero-drift input offset voltage over time and temperature. The zero-drift feature reduces the high 1/f noise typically found in CMOS input operational amplifiers, making it useful for a wide variety of low-frequency measurement applications. The MAX9617 and MAX9619 are available in a space-saving, 2mm x 2mm, 6-pin SC70 package. The MAX9619 features a power-saving shutdown mode. The MAX9618 is available in a 2mm x 2mm, 8-pin SC70 package. The MAX9620 is available in a 2mm x 2mm, 5-pin SC70 package. All devices are specified over the -40°C to +125°C automotive operating temperature range.

II. Manufacturing Information

A. Description/Function:	High-Efficiency, 1.5MHz Op Amps with RRIO
B. Process:	S18
C. Number of Device Transistors:	1444
D. Fabrication Location:	California
E. Assembly Location:	Thailand
F. Date of Initial Production:	January 21, 2010

III. Packaging Information

A. Package Type:	8L SC70
B. Lead Frame:	Copper
C. Lead Finish:	NiPdAu
D. Die Attach:	Non-conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-3992
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	1
J. Single Layer Theta Ja:	326°C/W
K. Single Layer Theta Jc:	115°C/W
L. Multi Layer Theta Ja:	326°C/W
M. Multi Layer Theta Jc:	115°C/W

IV. Die Information

A. Dimensions:	32.68 X 40.94 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.18um
F. Minimum Metal Spacing:	0.18um
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Richard Aburano (Manager, Reliability Engineering) Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135¿C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 48 \times 2}$$

(Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 22.9 \times 10^{-9}$

λ = 22.9 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maximintegrated.com/qa/reliability/monitor. Cumulative monitor data for the S18 Process results in a FIT Rate of 0.40 @ 25C and 6.96 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot SC3ZAQ001D D/C 0940)

The OY41 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA and overvoltage per JEDEC JESD78.

Table 1

Reliability Evaluation Test Results

MAX9618AXA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	48	0	SC3ZAQ001D, D/C 0940

Note 1: Life Test Data may represent plastic DIP qualification lots.